

# CD4020B, CD4024B, CD4040B Types

## CMOS Ripple-Carry Binary Counter/Dividers

High-Voltage Types (20-Volt Rating)

CD4020B – 14 Stage

CD4024B – 7 Stage

CD4040B – 12 Stage

■ CD4020B, CD4024B, and CD4040B are ripple-carry binary counters. All counter stages are master-slave flip-flops. The state of a counter advances one count on the negative transition of each input pulse; a high level on the RESET line resets the counter to its all zeros state. Schmitt trigger action on the input-pulse line permits unlimited rise and fall times. All inputs and outputs are buffered.

The CD4020B and CD4040B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes). The CD4040B type also is supplied in 16-lead small-outline packages (M and M96 suffixes).

The CD4024B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

### MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ )

Voltages referenced to  $V_{SS}$  Terminal) ..... -0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to  $V_{DD}$  +0.5V

DC INPUT CURRENT, ANY ONE INPUT .....  $\pm 10\text{mA}$

POWER DISSIPATION PER PACKAGE ( $P_D$ ):

For  $T_A = -55^\circ\text{C}$  to  $+100^\circ\text{C}$  ..... 500mW

For  $T_A = +100^\circ\text{C}$  to  $+125^\circ\text{C}$  ..... Derate Linearly at 12mW/ $^\circ\text{C}$  to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR  $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$  ..... 100mW

OPERATING-TEMPERATURE RANGE ( $T_A$ ) .....  $-55^\circ\text{C}$  to  $+125^\circ\text{C}$

STORAGE TEMPERATURE RANGE ( $T_{stg}$ ) .....  $-65^\circ\text{C}$  to  $+150^\circ\text{C}$

LEAD TEMPERATURE (DURING SOLDERING):

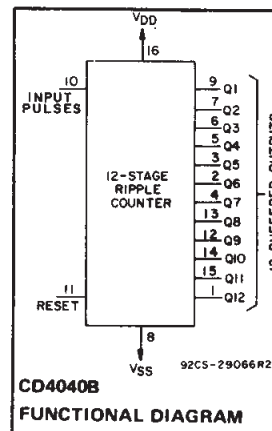
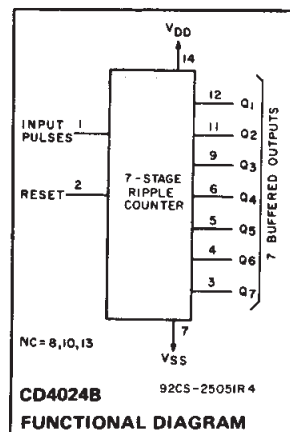
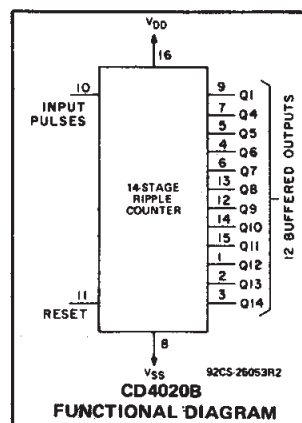
At distance  $1/16 \pm 1/32$  inch ( $1.59 \pm 0.79\text{mm}$ ) from case for 10s max .....  $+265^\circ\text{C}$

### Features:

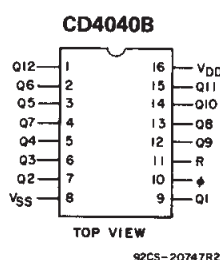
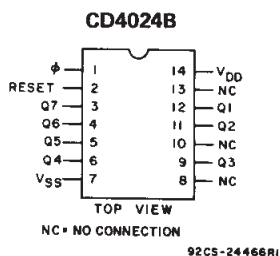
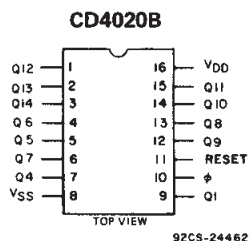
- Medium-speed operation
- Fully static operation
- Buffered inputs and outputs
- 100% tested for quiescent current at 20 V
- Standardized, symmetrical output characteristics
- Fully static operation
- Common reset
- 5-V, 10-V, and 15-V parametric ratings
- Maximum input current of  $1\text{ }\mu\text{A}$  at 18 V over full package-temperature range;  $100\text{ nA}$  at 18 V and  $25^\circ\text{C}$
- Noise margin (over full package-temperature range):
  - 1 V at  $V_{DD} = 5\text{ V}$
  - 2 V at  $V_{DD} = 10\text{ V}$
  - 2.5 V at  $V_{DD} = 15\text{ V}$
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

### Applications:

- Control counters
- Frequency dividers
- Timers
- Time-delay circuits



### TERMINAL ASSIGNMENTS



## CD4020B, CD4024B, CD4040B Types

**RECOMMENDED OPERATING CONDITIONS** at  $T_A = 25^\circ\text{C}$ , Unless Otherwise Specified  
 For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

| CHARACTERISTIC                                                           | $V_{DD}$      | Min.              | Max.           | UNITS         |
|--------------------------------------------------------------------------|---------------|-------------------|----------------|---------------|
| Supply Voltage Range (at $T_A = \text{Full Package-Temperature Range}$ ) |               | 3                 | 18             | V             |
| Input-Pulse Frequency, $f_\phi$                                          | 5<br>10<br>15 | —<br>—<br>—       | 3.5<br>8<br>12 | MHz           |
| Input-Pulse Width, $t_W$                                                 | 5<br>10<br>15 | 140<br>60<br>40   | —<br>—<br>—    | ns            |
| Input-Pulse Rise or Fall Time, $t_{r\phi}, t_{f\phi}$                    | 5<br>10<br>15 | Unlimited         | —              | $\mu\text{s}$ |
| Reset Pulse Width, $t_W$                                                 | 5<br>10<br>15 | 200<br>80<br>60   | —              | ns            |
| Reset Removal Time, $t_{REM}$                                            | 5<br>10<br>15 | 350<br>150<br>100 | —              | ns            |

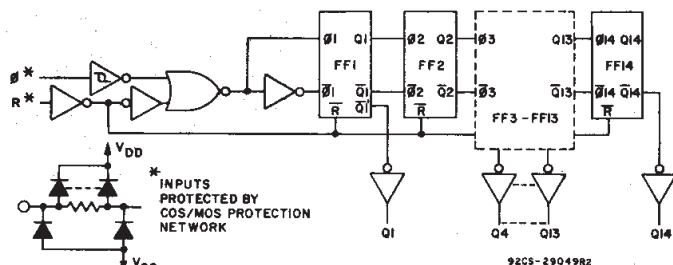


Fig. 1 — Logic diagram for CD4020B.

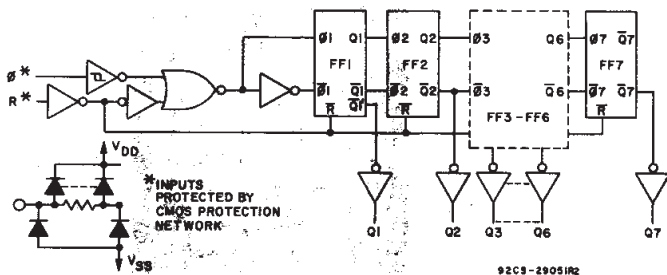


Fig. 2 — Logic diagram for CD4024B.

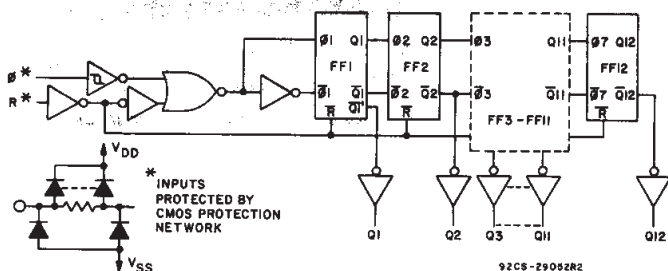


Fig. 3 — Logic diagram for CD4040B.

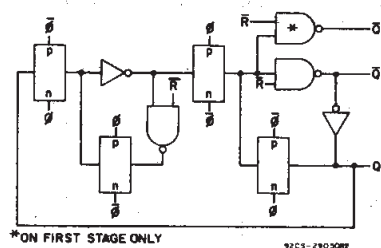


Fig. 4 — Detail of typical flip-flop stage.

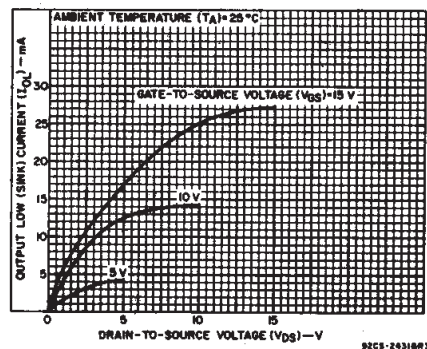


Fig. 5 — Typical output low (sink) current characteristics.

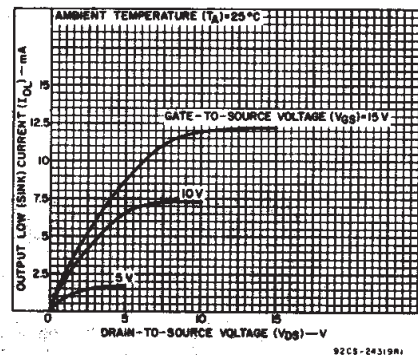


Fig. 6 — Minimum output low (sink) current characteristics.

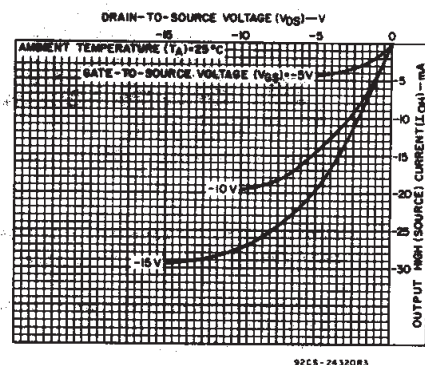


Fig. 7 — Typical output high (source) current characteristics.

# CD4020B, CD4024B, CD4040B Types

## STATIC ELECTRICAL CHARACTERISTICS

| CHARACTER-<br>ISTIC                                         | CONDITIONS            |                        |                        | LIMITS AT INDICATED TEMPERATURES (°C) |       |       |       |       |                   |      | UNITS |
|-------------------------------------------------------------|-----------------------|------------------------|------------------------|---------------------------------------|-------|-------|-------|-------|-------------------|------|-------|
|                                                             | V <sub>O</sub><br>(V) | V <sub>IN</sub><br>(V) | V <sub>DD</sub><br>(V) | +25                                   |       |       |       |       |                   |      |       |
|                                                             |                       |                        |                        | -55                                   | -40   | +85   | +125  | Min.  | Typ.              | Max. |       |
| Quiescent Device<br>Current,<br>I <sub>DD</sub> Max.        | —                     | 0,5                    | 5                      | 5                                     | 5     | 150   | 150   | —     | 0.04              | 5    | μA    |
|                                                             | —                     | 0,10                   | 10                     | 10                                    | 10    | 300   | 300   | —     | 0.04              | 10   |       |
|                                                             | —                     | 0,15                   | 15                     | 20                                    | 20    | 600   | 600   | —     | 0.04              | 20   |       |
|                                                             | —                     | 0,20                   | 20                     | 100                                   | 100   | 3000  | 3000  | —     | 0.08              | 100  |       |
| Output Low<br>(Sink) Current<br>I <sub>OL</sub> Min.        | 0.4                   | 0,5                    | 5                      | 0.64                                  | 0.61  | 0.42  | 0.36  | 0.51  | 1                 | —    | mA    |
|                                                             | 0.5                   | 0,10                   | 10                     | 1.6                                   | 1.5   | 1.1   | 0.9   | 1.3   | 2.6               | —    |       |
|                                                             | 1.5                   | 0,15                   | 15                     | 4.2                                   | 4     | 2.8   | 2.4   | 3.4   | 6.8               | —    |       |
| Output High<br>(Source)<br>Current,<br>I <sub>OH</sub> Min. | 4.6                   | 0,5                    | 5                      | -0.64                                 | -0.61 | -0.42 | -0.36 | -0.51 | -1                | —    | mA    |
|                                                             | 2.5                   | 0,5                    | 5                      | -2                                    | -1.8  | -1.3  | -1.15 | -1.6  | -3.2              | —    |       |
|                                                             | 9.5                   | 0,10                   | 10                     | -1.6                                  | -1.5  | -1.1  | -0.9  | -1.3  | -2.6              | —    |       |
|                                                             | 13.5                  | 0,15                   | 15                     | -4.2                                  | -4    | -2.8  | -2.4  | -3.4  | -6.8              | —    |       |
| Output Voltage:<br>Low-Level,<br>V <sub>OL</sub> Max.       | —                     | 0,5                    | 5                      | 0.05                                  |       |       |       | —     | 0                 | 0.05 | V     |
|                                                             | —                     | 0,10                   | 10                     | 0.05                                  |       |       |       | —     | 0                 | 0.05 |       |
|                                                             | —                     | 0,15                   | 15                     | 0.05                                  |       |       |       | —     | 0                 | 0.05 |       |
| Output Voltage:<br>High-Level,<br>V <sub>OH</sub> Min.      | —                     | 0,5                    | 5                      | 4.95                                  |       |       |       | 4.95  | 5                 | —    | V     |
|                                                             | —                     | 0,10                   | 10                     | 9.95                                  |       |       |       | 9.95  | 10                | —    |       |
|                                                             | —                     | 0,15                   | 15                     | 14.95                                 |       |       |       | 14.95 | 15                | —    |       |
| Input Low<br>Voltage,<br>V <sub>IL</sub> Max.               | 0.5, 4.5              | —                      | 5                      | 1.5                                   |       |       |       | —     | —                 | 1.5  | V     |
|                                                             | 1, 9                  | —                      | 10                     | 3                                     |       |       |       | —     | —                 | 3    |       |
|                                                             | 1.5,13.5              | —                      | 15                     | 4                                     |       |       |       | —     | —                 | 4    |       |
| Input High<br>Voltage,<br>V <sub>IH</sub> Min.              | 0.5, 4.5              | —                      | 5                      | 3.5                                   |       |       |       | 3.5   | —                 | —    | V     |
|                                                             | 1, 9                  | —                      | 10                     | 7                                     |       |       |       | 7     | —                 | —    |       |
|                                                             | 1.5,13.5              | —                      | 15                     | 11                                    |       |       |       | 11    | —                 | —    |       |
| Input Current<br>I <sub>IN</sub> Max.                       | —                     | 0,18                   | 18                     | ±0.1                                  | ±0.1  | ±1    | ±1    | —     | ±10 <sup>-5</sup> | ±0.1 | μA    |

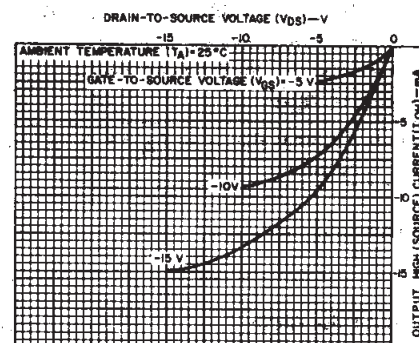


Fig. 8 — Minimum output high (source) current characteristics.



Fig. 9 — Typical transition time as a function of load capacitance.



Dimensions and Pad Layout for CD4020BH. Dimensions and pad layout for CD4040BH are identical.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10<sup>-3</sup> inch).



Dimensions and Pad Layout for CD4024BH.

# CD4020B, CD4024B, CD4040B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at  $T_A = 25^\circ\text{C}$ , Input  $t_r, t_f = 20\text{ ns}$ ,  
 $C_L = 50\text{ pF}$ ,  $R_L = 200\text{ k}\Omega$

| CHARACTERISTIC                                                                               | TEST<br>CONDITIONS | V <sub>DD</sub><br>(V) | LIMITS    |      |      | UNITS |
|----------------------------------------------------------------------------------------------|--------------------|------------------------|-----------|------|------|-------|
|                                                                                              |                    |                        | Min.      | Typ. | Max. |       |
| Input-Pulse Operation                                                                        |                    |                        |           |      |      |       |
| Propagation Delay Time, $\phi$ to<br>Q <sub>1</sub> Out; t <sub>PHL</sub> , t <sub>PLH</sub> |                    | 5                      | —         | 180  | 360  | ns    |
|                                                                                              |                    | 10                     | —         | 80   | 160  |       |
|                                                                                              |                    | 15                     | —         | 65   | 130  |       |
| Q <sub>n</sub> to Q <sub>n</sub> + 1;<br>t <sub>PHL</sub> , t <sub>PLH</sub>                 |                    | 5                      | —         | 100  | 330  | ns    |
|                                                                                              |                    | 10                     | —         | 40   | 80   |       |
|                                                                                              |                    | 15                     | —         | 30   | 60   |       |
| Transition Time,<br>t <sub>THL</sub> , t <sub>TLH</sub>                                      |                    | 5                      | —         | 100  | 200  | ns    |
|                                                                                              |                    | 10                     | —         | 50   | 100  |       |
|                                                                                              |                    | 15                     | —         | 40   | 80   |       |
| Minimum Input-Pulse<br>Width, t <sub>W</sub>                                                 |                    | 5                      | —         | 70   | 140  | ns    |
|                                                                                              |                    | 10                     | —         | 30   | 60   |       |
|                                                                                              |                    | 15                     | —         | 20   | 40   |       |
| Input-Pulse Rise or Fall<br>Time, t <sub>rφ</sub> , t <sub>fφ</sub>                          |                    | 5                      | Unlimited |      |      | μs    |
|                                                                                              |                    | 10                     |           |      |      |       |
|                                                                                              |                    | 15                     |           |      |      |       |
| Maximum Input-Pulse<br>Frequency, f <sub>φ</sub>                                             |                    | 5                      | 3.5       | 7    | —    | MHz   |
|                                                                                              |                    | 10                     | 8         | 16   | —    |       |
|                                                                                              |                    | 15                     | 12        | 24   | —    |       |
| Input Capacitance, C <sub>I</sub>                                                            | Any Input          |                        | —         | 5    | 7.5  | pF    |
| Reset Operation                                                                              |                    |                        |           |      |      |       |
| Propagation Delay<br>Time, t <sub>PHL</sub>                                                  |                    | 5                      | —         | 140  | 280  | ns    |
|                                                                                              |                    | 10                     | —         | 60   | 120  |       |
|                                                                                              |                    | 15                     | —         | 50   | 100  |       |
| Minimum Reset Pulse<br>Width, t <sub>W</sub>                                                 |                    | 5                      | —         | 100  | 200  | ns    |
|                                                                                              |                    | 10                     | —         | 40   | 80   |       |
|                                                                                              |                    | 15                     | —         | 30   | 60   |       |
| Reset Removal Time,<br>t <sub>REM</sub>                                                      |                    | 5                      | —         | 175  | 350  | ns    |
|                                                                                              |                    | 10                     | —         | 75   | 150  |       |
|                                                                                              |                    | 15                     | —         | 50   | 100  |       |

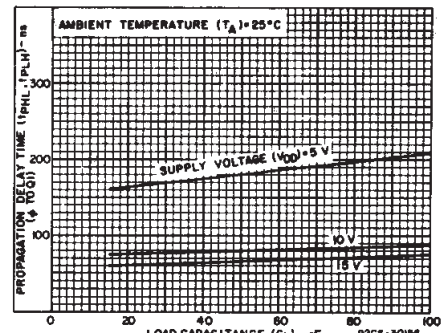


Fig. 10 - Typical propagation delay time as a function of load capacitance ( $\phi$  to  $Q_1$ ).

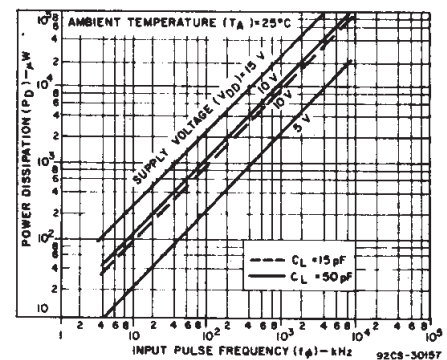


Fig. 11 - Typical dynamic power dissipation as a function of input pulse frequency for CD4020B.

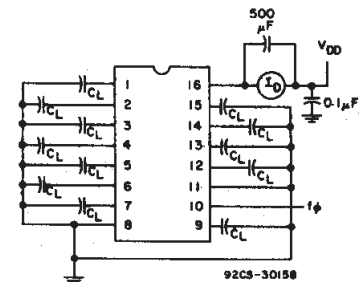


Fig. 12 - Dynamic power dissipation test circuit for CD4020B.

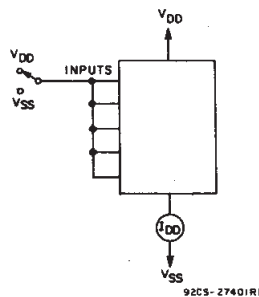


Fig. 13 - Quiescent device current test circuit.

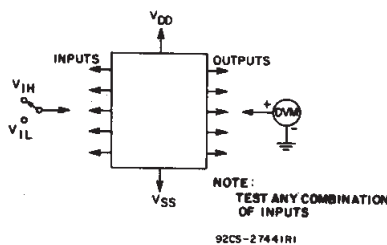


Fig. 14 - Input voltage test circuits.

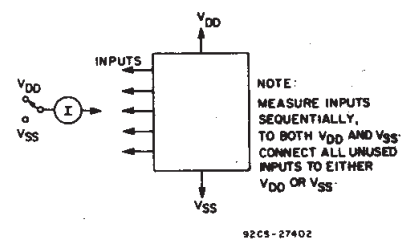


Fig. 15 - Input current test circuit.

**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup>    | Lead/<br>Ball Finish | MSL Peak Temp <sup>(3)</sup> | Samples<br>(Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| 89271AKB3T       | OBSOLETE              | CFP          | WR              | 16   |             | TBD                        | Call TI              | Call TI                      |                             |
| 89274AKB3T       | OBSOLETE              | CFP          | WR              | 16   |             | TBD                        | Call TI              | Call TI                      |                             |
| CD4020BE         | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD4020BEE4       | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD4020BF         | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD4020BF3A       | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD4020BNSR       | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4020BNSRE4     | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4020BNSRG4     | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4020BPW        | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4020BPWE4      | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4020BPWG4      | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4020BPWR       | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4020BPWRE4     | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4020BPWRG4     | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BE         | ACTIVE                | PDIP         | N               | 14   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD4024BEE4       | ACTIVE                | PDIP         | N               | 14   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD4024BF         | ACTIVE                | CDIP         | J               | 14   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD4024BF3A       | ACTIVE                | CDIP         | J               | 14   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD4024BF3AS2534  | OBSOLETE              | CDIP         | J               | 14   |             | TBD                        | Call TI              | Call TI                      |                             |
| CD4024BM         | ACTIVE                | SOIC         | D               | 14   | 50          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup>    | Lead/<br>Ball Finish | MSL Peak Temp <sup>(3)</sup> | Samples<br>(Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| CD4024BM96       | ACTIVE                | SOIC         | D               | 14   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BM96E4     | ACTIVE                | SOIC         | D               | 14   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BM96G4     | ACTIVE                | SOIC         | D               | 14   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BME4       | ACTIVE                | SOIC         | D               | 14   | 50          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BMG4       | ACTIVE                | SOIC         | D               | 14   | 50          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BMT        | ACTIVE                | SOIC         | D               | 14   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BMTE4      | ACTIVE                | SOIC         | D               | 14   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BMTG4      | ACTIVE                | SOIC         | D               | 14   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BNSR       | ACTIVE                | SO           | NS              | 14   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BNSRE4     | ACTIVE                | SO           | NS              | 14   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BNSRG4     | ACTIVE                | SO           | NS              | 14   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BPW        | ACTIVE                | TSSOP        | PW              | 14   | 90          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BPWE4      | ACTIVE                | TSSOP        | PW              | 14   | 90          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BPWG4      | ACTIVE                | TSSOP        | PW              | 14   | 90          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BPWR       | ACTIVE                | TSSOP        | PW              | 14   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BPWRE4     | ACTIVE                | TSSOP        | PW              | 14   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4024BPWRG4     | ACTIVE                | TSSOP        | PW              | 14   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BE         | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD4040BEE4       | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup>    | Lead/<br>Ball Finish | MSL Peak Temp <sup>(3)</sup> | Samples<br>(Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| CD4040BF         | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD4040BF3A       | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD4040BM         | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BM96       | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BM96E4     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BM96G4     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BME4       | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BMG4       | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BNSR       | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BNSRE4     | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BNSRG4     | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BPW        | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BPWE4      | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BPWG4      | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BPWR       | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BPWRE4     | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD4040BPWRG4     | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| JM38510/05653BEA | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| JM38510/05655BCA | ACTIVE                | CDIP         | J               | 14   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| M38510/05653BEA  | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/ Ball Finish | MSL Peak Temp <sup>(3)</sup> | Samples (Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|-------------------|------------------------------|--------------------------|
| M38510/05655BCA  | ACTIVE                | CDIP         | J               | 14   | 1           | TBD                     | A42               | N / A for Pkg Type           |                          |

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF CD4020B, CD4020B-MIL, CD4024B, CD4024B-MIL, CD4040B, CD4040B-MIL :

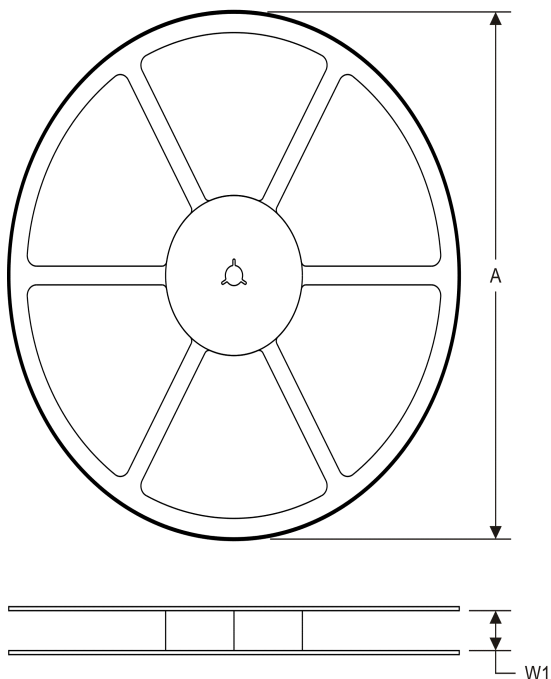
• Catalog: [CD4020B](#), [CD4024B](#), [CD4040B](#)

• Military: [CD4020B-MIL](#), [CD4024B-MIL](#), [CD4040B-MIL](#)

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

- 
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


|    |                                                           |
|----|-----------------------------------------------------------|
| A0 | Dimension designed to accommodate the component width     |
| B0 | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

| Device     | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD4020BNSR | SO           | NS              | 16   | 2000 | 330.0              | 16.4               | 8.2     | 10.5    | 2.5     | 12.0    | 16.0   | Q1            |
| CD4020BPWR | TSSOP        | PW              | 16   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| CD4024BM96 | SOIC         | D               | 14   | 2500 | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |
| CD4024BMT  | SOIC         | D               | 14   | 250  | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |
| CD4024BNSR | SO           | NS              | 14   | 2000 | 330.0              | 16.4               | 8.2     | 10.5    | 2.5     | 12.0    | 16.0   | Q1            |
| CD4024BPWR | TSSOP        | PW              | 14   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| CD4040BM96 | SOIC         | D               | 16   | 2500 | 330.0              | 16.4               | 6.5     | 10.3    | 2.1     | 8.0     | 16.0   | Q1            |
| CD4040BNSR | SO           | NS              | 16   | 2000 | 330.0              | 16.4               | 8.2     | 10.5    | 2.5     | 12.0    | 16.0   | Q1            |
| CD4040BPWR | TSSOP        | PW              | 16   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device     | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD4020BNSR | SO           | NS              | 16   | 2000 | 367.0       | 367.0      | 38.0        |
| CD4020BPWR | TSSOP        | PW              | 16   | 2000 | 367.0       | 367.0      | 35.0        |
| CD4024BM96 | SOIC         | D               | 14   | 2500 | 367.0       | 367.0      | 38.0        |
| CD4024BMT  | SOIC         | D               | 14   | 250  | 367.0       | 367.0      | 38.0        |
| CD4024BNSR | SO           | NS              | 14   | 2000 | 367.0       | 367.0      | 38.0        |
| CD4024BPWR | TSSOP        | PW              | 14   | 2000 | 367.0       | 367.0      | 35.0        |
| CD4040BM96 | SOIC         | D               | 16   | 2500 | 333.2       | 345.9      | 28.6        |
| CD4040BNSR | SO           | NS              | 16   | 2000 | 367.0       | 367.0      | 38.0        |
| CD4040BPWR | TSSOP        | PW              | 16   | 2000 | 367.0       | 367.0      | 35.0        |

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| PINS **<br>DIM | 14                     | 16                     | 18                     | 20                     |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A              | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX          | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN          | —                      | —                      | —                      | —                      |
| C MAX          | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN          | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

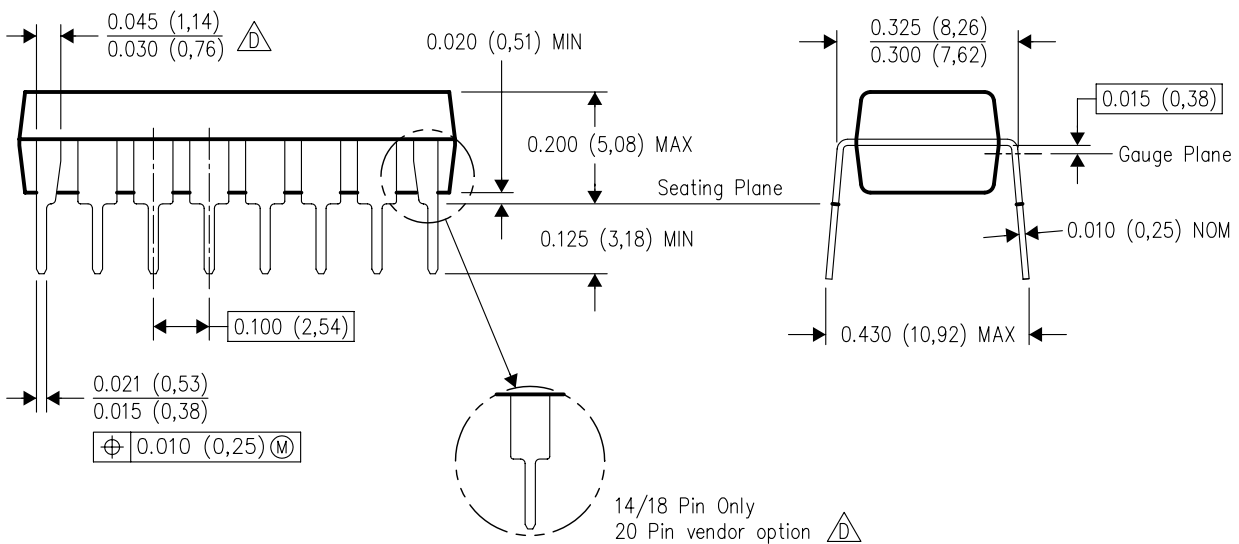
## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



| PINS **             | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| DIM                 |                  |                  |                  |                  |
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |



14/18 Pin Only  
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

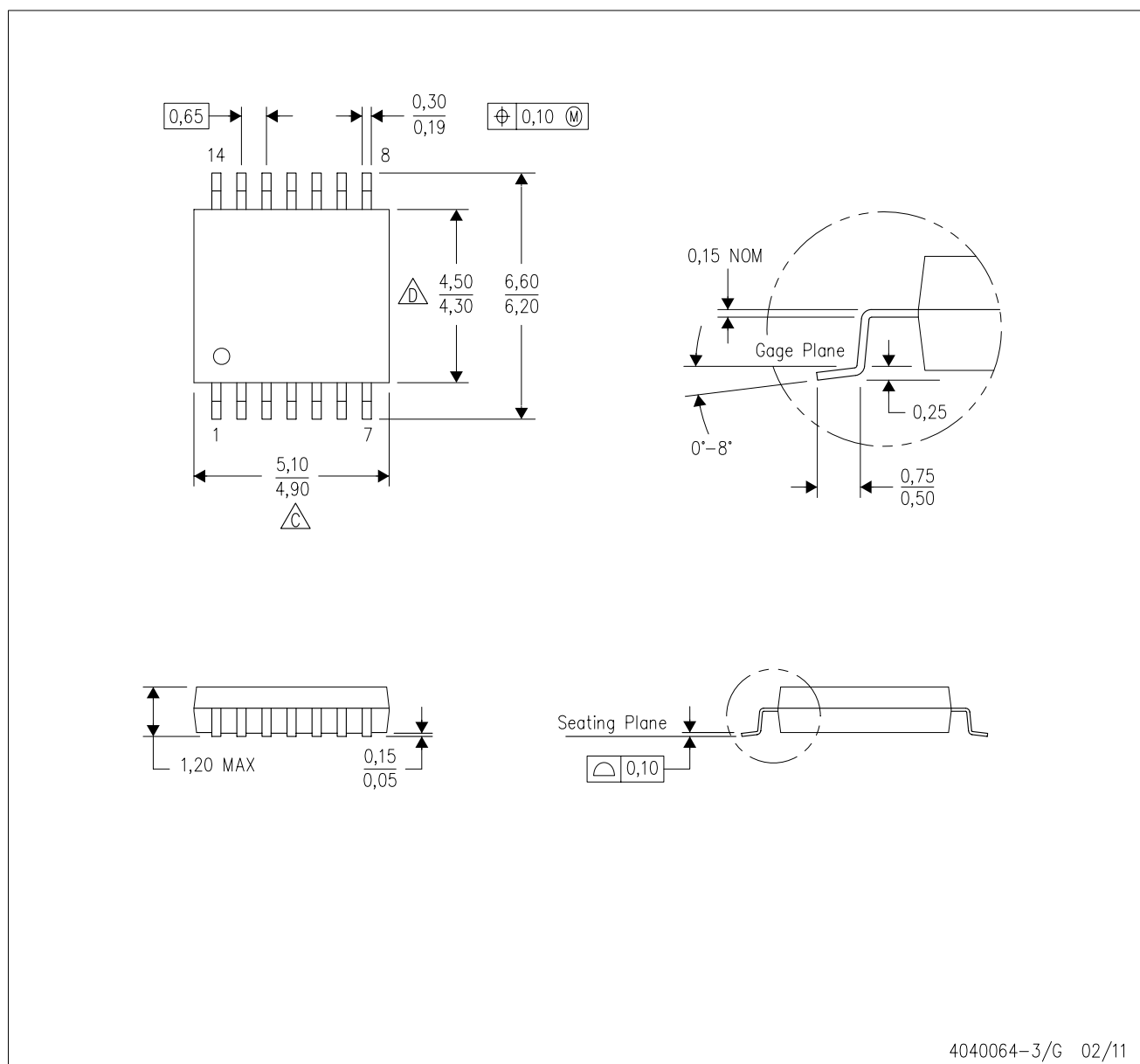
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

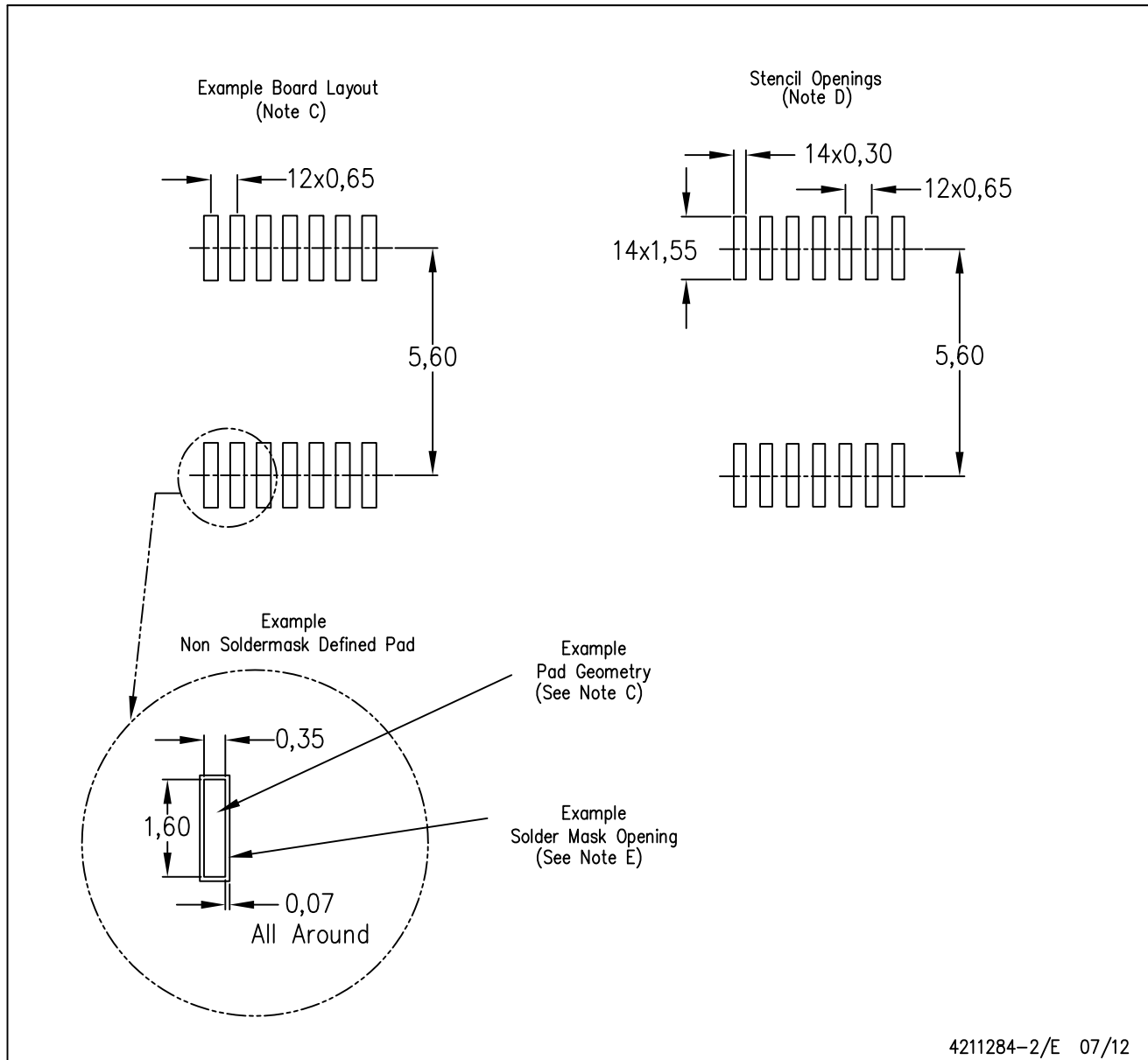
PLASTIC SMALL OUTLINE



4040064-3/G 02/11

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

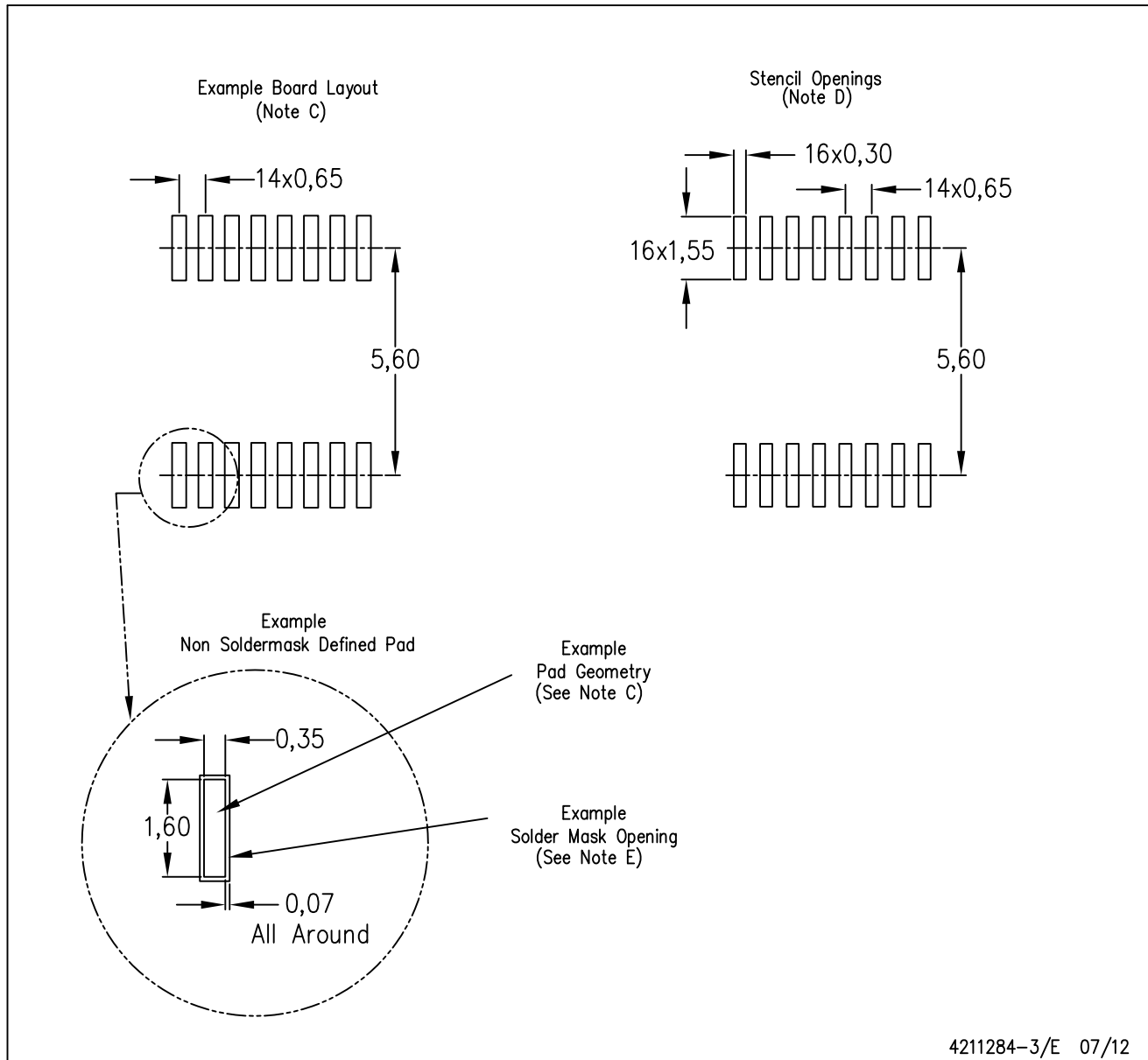
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - $\Delta$  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - $\Delta$  D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



| DIM \ PINS ** | 14    | 16    | 20    | 24    |
|---------------|-------|-------|-------|-------|
| A MAX         | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN         | 9,90  | 9,90  | 12,30 | 14,70 |

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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| Security                      | <a href="http://www.ti.com/security">www.ti.com/security</a>                             |
| Space, Avionics and Defense   | <a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a> |
| Video and Imaging             | <a href="http://www.ti.com/video">www.ti.com/video</a>                                   |

**TI E2E Community** [e2e.ti.com](http://e2e.ti.com)

## Данный компонент на территории Российской Федерации

**Вы можете приобрести в компании MosChip.**

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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